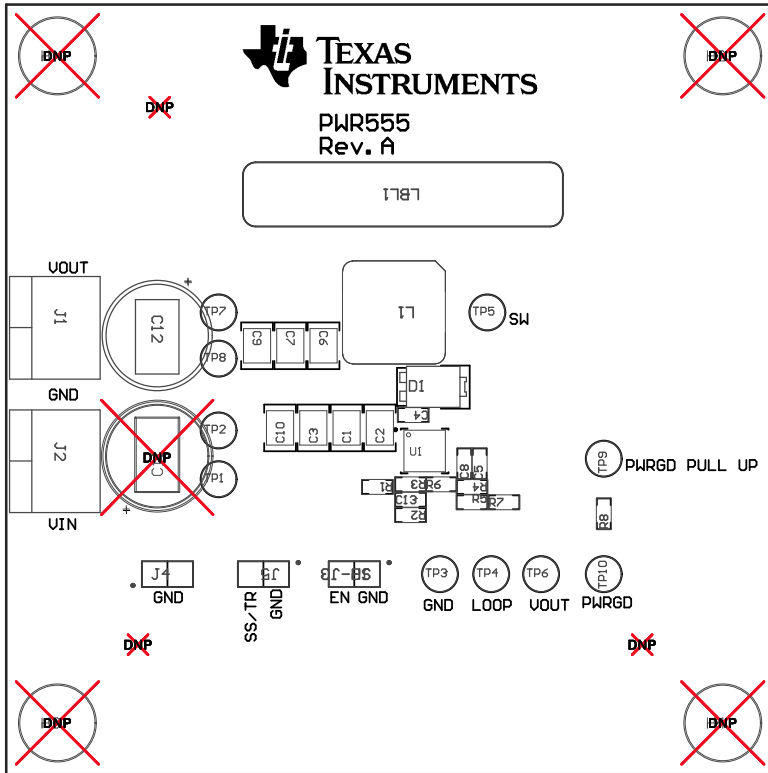


- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



TOP1 OVERLAY

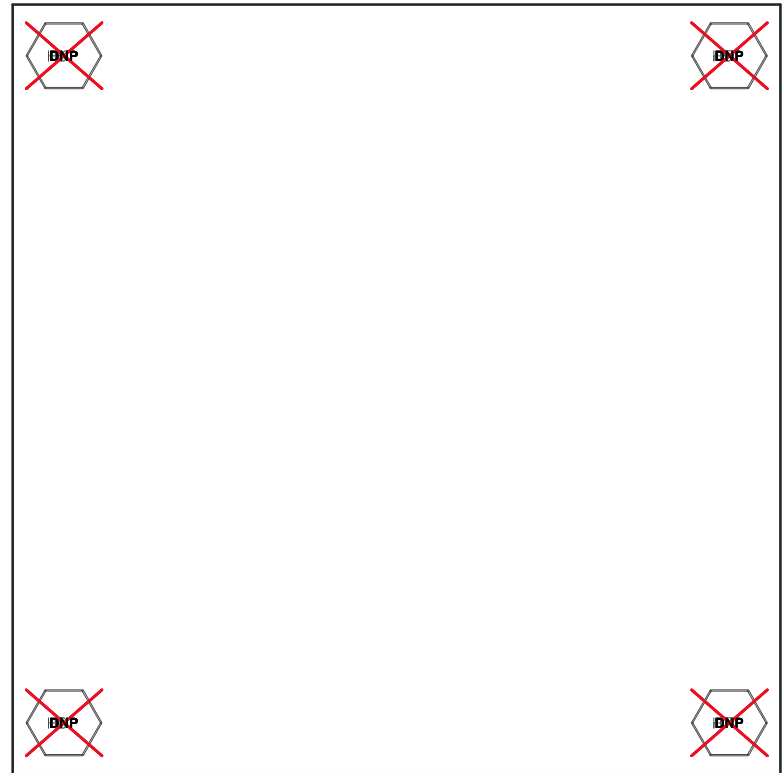
TABLE 1

Variant	Label text
001	TPS54561EVM-593
002	TPS54361EVM-593
003	TPS54541EVM-593
004	TPS54341EVM-593

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PWR555	REV: A	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 9/18/2013 7:05:14 PM	TEXAS INSTRUMENTS	

BOTTOM OVERLAY



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PWR555	REV: A	SUN REV: Not In VersionControl
	IGNORE -> Bottom Overlay		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 9/18/2013 7:05:14 PM	TEXAS INSTRUMENTS	

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